

Amendments to the Specification:

Please replace the paragraph beginning at page 1, line 7, with the following rewritten paragraph:

-- The present invention relates to a novel dicing and die bonding pressure-sensitive adhesive sheet. More particularly, the invention relates to a dicing and die bonding pressure-sensitive adhesive sheet that is particularly suitable for use in the process of dicing ~~and silicon~~ a silicon wafer or the like into chips and bonding the resultant chips onto die pads of a substrate such as a lead frame. --

Please replace the paragraph beginning at page 2, line 4, with the following rewritten paragraph:

-- These patent documents disclose pressure-sensitive adhesive sheets comprising a base material and a pressure-sensitive adhesive layer which is composed of a specific composition. The pressure-sensitive adhesive layers work to fix the wafer in the wafer dicing. The adhesion thereof with respect to the base material is controllable. Therefore, when the chips are picked up after the dicing, the pressure-sensitive adhesive layer can be removed from the base material together with the chips picked up. The IC chips on which the pressure-sensitive adhesive layer is adhered are then mounted on a substrate and heated. As a result, a thermosetting resin contained in the pressure-sensitive adhesive layer produces adhesion and the IC chips are ~~bonded~~ bonded on the substrate. --

Please replace the paragraph beginning at page 3, line 3, with the following rewritten paragraph:

-- Meanwhile, recent IC package structures have great variation. This has demanded diverse requirements on properties depending on the structures. For example, structures of die pads on which the chips are mounted have been diversified and often have irregularities caused by copper wiring or solder resists. The ~~high~~ height difference caused by irregularities may be about 5 to 20 μm . When the die pads have such great height differences, the mounting of chips through the pressure-sensitive adhesive layer occasionally results in voids between the die pads and the pressure-

sensitive adhesive layer because the pressure-sensitive adhesive fails to densely embed the irregularities on the die pads. --

Please replace the paragraph beginning at page 32, line 21, with the following rewritten paragraph:

-- The chips with the pressure-sensitive adhesive layer were each mounted, via the adhesive layer, on a die pad of an IC package substrate and was were compression bonded thereto at 120°C and 150 MPa in 1 sec. The IC package substrate used herein was a laminate of a 50 µm polyimide film and a 20 µm electrodeposited copper foil, and had a die pad composed of a gold deposit disposed on a palladium deposit that was patterned on the copper foil, and also had a 25 µm high solder resist. The compression bonding was followed by further heating at 160°C for 60 min to cure the pressure-sensitive adhesive layer. Thereafter, a molding resin (containing biphenyl epoxy resin and phenol novolak resin) was applied on the chip-mounted surface of the substrate and molded the chip in desired shape. The molding resin was then cured by being heated at 175°C for 6 hr, and thereby the chip was high-pressure sealed. Onto the unsealed surface of the substrate, lead-free solder balls having a diameter of 0.5 mm were attached by a given method. Thus, a BGA (ball grid allay array) IC package was produced. --